

Electroplating

PALLUNA® 452 PALLADIUM ELECTROLYTE



Pure palladium electrolyte with excellent bonding and solderability

PALLUNA® 452 is a weakly ammoniacal electrolyte for the deposition of palladium in continuous systems and rack plating. It is used especially where excellent bondability and solderability are required.

The electrolyte has already been used for years in semiconductor technology and is mainly used in selective high-speed deposition. It is particularly suitable for systems with immersion cells, belt cells, brush cells, jet and spot systems.



Advantages

- Excellent bonding and solderability
- \cdot High deposition rate
- Simple electrolyte feed
- For continuous lines and rack plating

Applications

 \cdot Lead frames

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TECHNICAL SPECIFICATIONS

Electrolyte characteristics	
Electrolyte type	weakly ammoniacal
Metal content	3 (2.5 - 7) g/l Pd
pH value	8.0 (7.5 - 8.4)
Temperature	55 (50 - 60) °C
Current density range (depending on equipment)	1 - 2 A/dm ²
Plating speed	ca. 0.25 µm/min bei 1 A/dm² ca. 0.50 µm/min bei 2 A/dm²
Anode material	PLATINODE [®] 167

Coating characteristics	
Coating	Pure palladium
Purity of deposit	99.9 wt.% Pd
Color of deposit	white
Brightness	matt
Max. coating thickness	approx. 0.3 µm
Density	approx. 12 g/cm³

YOUR CONTACT

Do you have a specific question or would you like a no-obligation quote calculation? Our specialist will be happy to help you with any technical questions you might have.



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